

7/23/07

RESPONSE UNDER 37 C.F.R. § 1.116
EXPEDITED PROCEDURE
GROUP 1714
PATENT APPLICATION

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re application of

Docket No: Q78154

Kenichi OHKAWA, et al.

Appln. No.: 10/694,724

Group Art Unit: 1714

Confirmation No.: 4042

Examiner: Sandra K. Poulos

Filed: October 29, 2003

For: THERMOPLASTIC RESIN COMPOSITION AND ITS INJECTION MOLDED
ARTICLE

RESPONSE UNDER 37 C.F.R. § 1.116

MAIL STOP AF

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

Sir:

In response to the Office Action dated August 28, 2006, time for responding to which being extended to February 28, 2007, please consider the remarks as submitted herewith on the accompanying pages.

REMARKS

Claims 1-8 are all the claims pending in the application.

Claims 1-5 and 7-8 have been rejected under 35 U.S.C. § 103, as allegedly being unpatentable over U.S. Published Application No. 2002/0004546 to Ohkawa, *et al.* ("Ohkawa '546") in view of U.S. Published Application No. 2004/0053064 to Masuda, *et al.* ("Masuda '064").